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Part Number: [0541323862](#)
Status: **Active**
Overview: [ffc_fpc_smt](#)
Description: 0.50mm (.020") Pitch FFC/FPC Connector, Right Angle, SMT, ZIF, Bottom Contact Style, 38 Circuits, 0.1µm (4µ") Gold (Au) Contact Plating

Documents:

3D Model	Product Specification PS-54132-061 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

UL	E29179
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General

Product Family	FFC/FPC Connectors
Series	54132
Overview	ffc_fpc_smt
Product Name	N/A

Physical

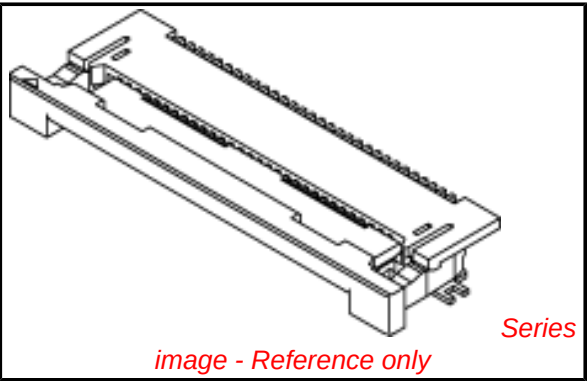
Circuits (Loaded)	38
Color - Resin	Black, Natural
Contact Position	Bottom
Durability (mating cycles max)	20
Entry Angle	90° Angle
Flammability	94V-0
Mated Height (in)	0.079 In
Mated Height (mm)	2.00 mm
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Rows	1
Orientation	Right Angle
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.020 In
Pitch - Mating Interface (mm)	0.50 mm
Plating min: Mating (µin)	4
Plating min: Mating (µm)	0.1
Plating min: Termination (µin)	2
Plating min: Termination (µm)	0.05
Polarized to PCB	Yes
Stackable	No
Surface Mount Compatible (SMC)	N/A
Temperature Range - Operating	-20°C to +85°C
Termination Interface: Style	Surface Mount
Wire/Cable Type	FFC/FPC

Electrical

Current - Maximum per Contact	0.5A
Voltage - Maximum	50V

Material Info

Reference - Drawing Numbers



EU RoHS

**ELV and RoHS
Compliant**

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

China RoHS



Search Parts in this Series

[54132Series](#)

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10 9 8 7 6 5 4 3 2 1

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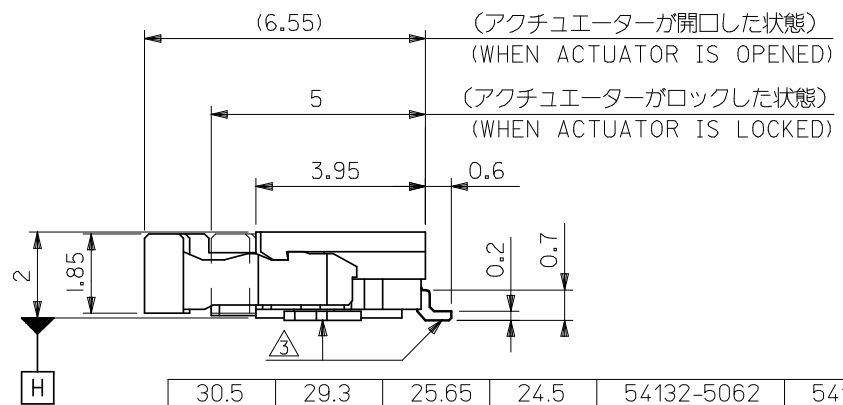
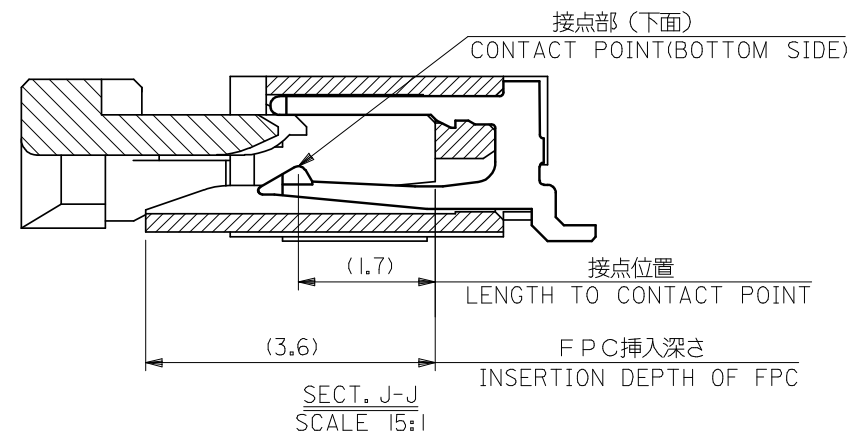
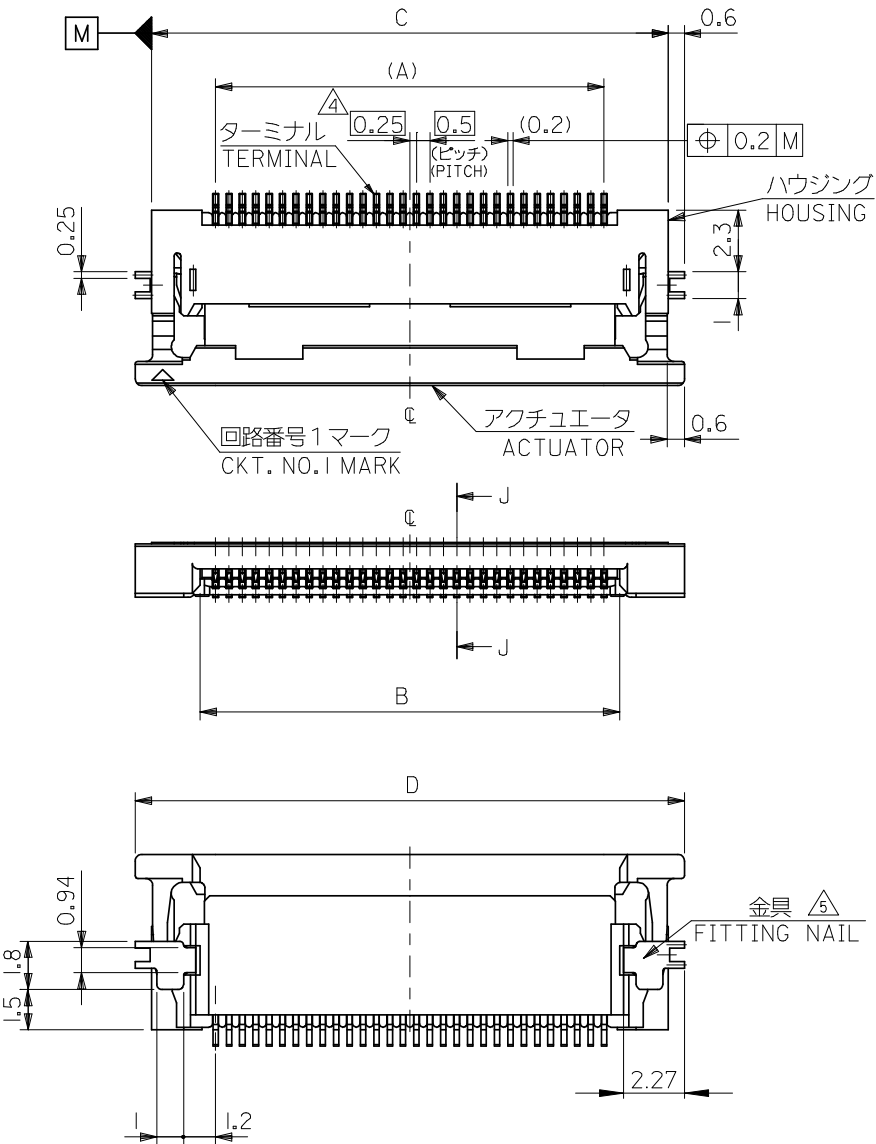
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30.5	29.3	25.65	24.5	54132-5062	54132-5068	50
28.0	26.8	23.15	22.0	54132-4562	54132-4568	45
27.0	25.8	22.15	21.0	54132-4362	54132-4368	43
25.5	24.3	20.65	19.5	54132-4062	54132-4068	40
24.5	23.3	19.65	18.5	54132-3862	54132-3868	38
23.5	22.3	18.65	17.5	54132-3662	54132-3668	36
23.0	21.8	18.15	17.0	54132-3562	54132-3568	35
22.5	21.3	17.65	16.5	54132-3462	54132-3468	34
22.0	20.8	17.15	16.0	54132-3362	54132-3368	33
21.5	20.3	16.65	15.5	54132-3262	54132-3268	32
20.5	19.3	15.65	14.5	54132-3062	54132-3068	30
D	C	B	A	EMBOSSED TAPE		MATERIAL. NO.
				ORDER No. オーダー番号		CKT.

REVISED EC NO: J2008-4308 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M.UMEDA		DATE 2004/09/27	TITLE 0.5 FPC CONN. HSG ASSY BTM CONTACT GOLD PLATING -LEAD FREE-(NI-BARRIER)			
		10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA		DATE 2004/09/27				
		30 OVER	±0.3	APPROVED BY N.UKITA		DATE 2004/09/27	MOLEX INCORPORATED			
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-54132-064		1 OF 4		
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

F

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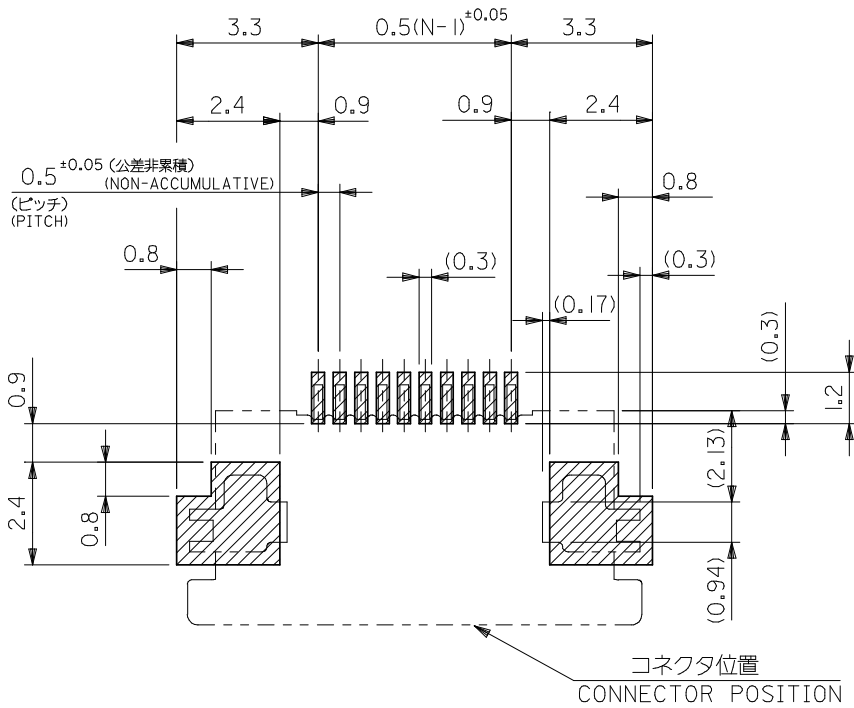
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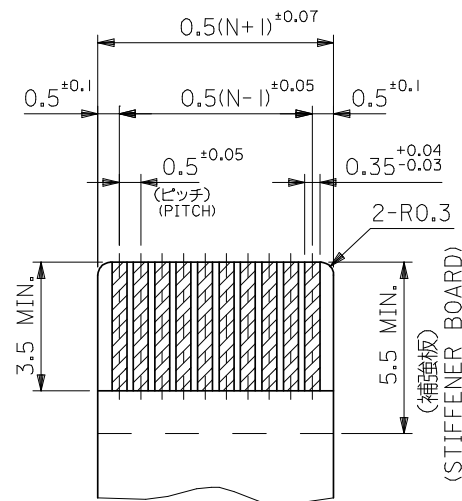
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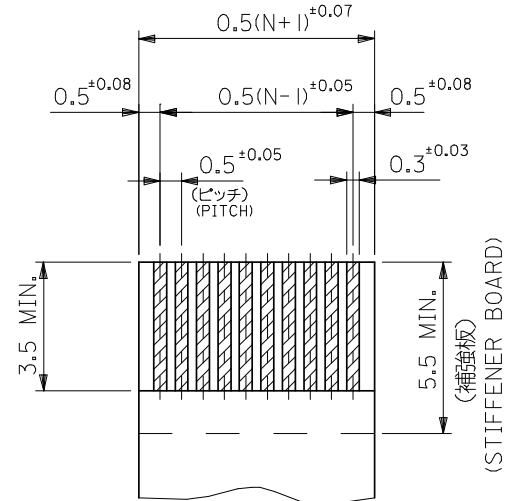
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参考基板レイアウト
RECOMMENDED PC BOARD PATTERN DIMENSION(REF.)
(マウント面)
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

注記
NOTES

1. 使用材料
MATERIAL
ハウジング
HOUSING : 46ナイロン, UL94V-0
: 46NYLON
- アクチュエーター
ACTUATOR : PPS, UL94V-0
: PPS
- ターミナル
: 金メッキ
コンタクト部 0.1 MICRO METER MIN.
テール部 0.05 MICRO METER MIN.
: ニッケル下地 1.0 MICRO METER MIN.
- TERMINAL : GOLD PLATING
CONTACT PORTION: 0.1 MICRO METER MIN.
TAIL PORTION: 0.05 MICRO METER MIN.
: NI-PLATING: 0.1 MICRO METER MIN.
- 金具 : リン青銅 (t=0.2), 鍍メッキ 1.0~3.0 MICRO METER MIN.
: ニッケル下地 1.0~3.0 MICRO METER MIN.
- FITTING NAIL : PHOS-BRO, TIN-PLATE 1.0~3.0 MICRO METER MIN.
OVER NICKEL 1.0~3.0 MICRO METER MIN.

2. エンボステープ梱包時は、アクチュエーターがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54132-**69 SHOULD BE LOCKED.
3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 [H] に対し上方向 0.1 MAX.、下方向 0.15 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAIL FROM [H] UPPER DIRECTION: 0.1 MAX., LOWER DIRECTION: 0.15 MAX.
4. 偶数極に適用
APPLY FOR EVEN CIRCUIT.
5. パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
6. 本製品は54132-**61に対するニッケルバリア品である。
THIS PRODUCT IS Ni-Barrier OF 54132-**61.

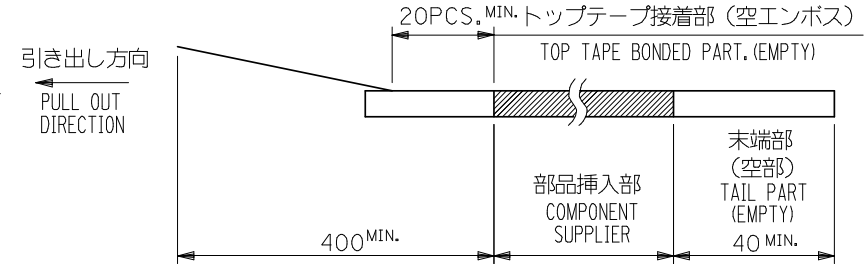
FPC/FFCについて:
打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートル
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC.:
THICKNESS OF SOFT COPPER FOIL : 35 micrometer or 50 micrometer

FPCについて:
補強フィルム材質はポリイミドを推奨いたします。
接着剤は熱硬化接着剤を推奨いたします。
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

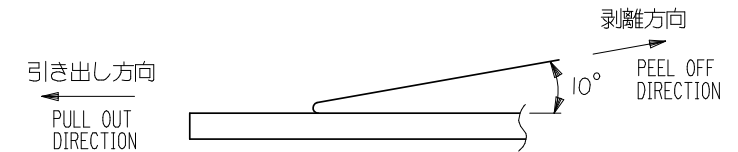
REVISED EC NO: J2008-4308 DRWN:MABEI CHKD:THARYAWA APPR:NUKITA	DESCRIPTION 2008/06/27 2008/06/30 2008/06/30	REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
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			10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE 2004/09/27				
			30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2004/09/27				 MOLEX INCORPORATED
			ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.	SHEET NO.		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-54132-064	2 OF 4		
					SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

NOTES

- 梱包数量：1500個／リール
NUMBER OF CONNECTORS : 1500PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



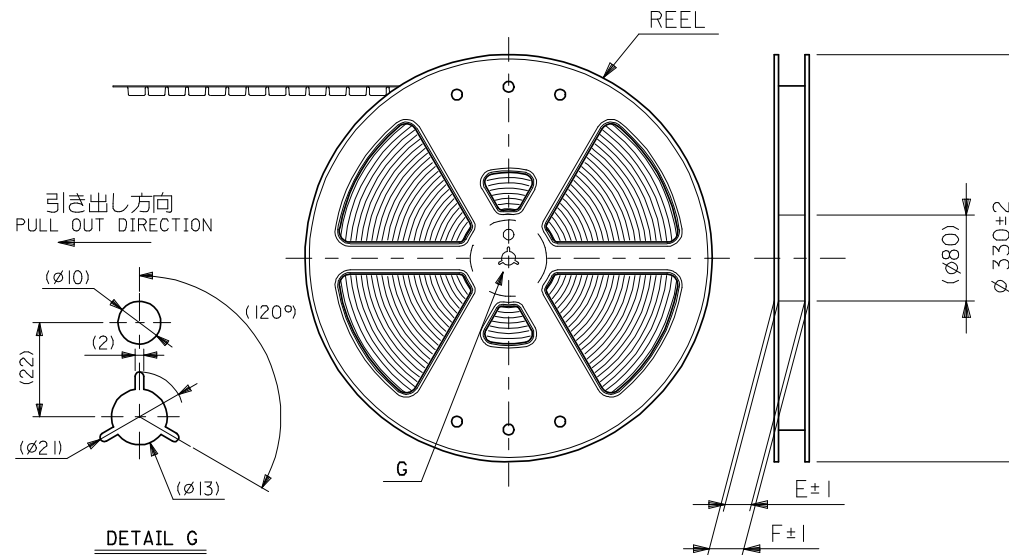
- トップテープの剥離強度：0.1N ～ 1.3N (10gf ～ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ～ 1.3N (10gf ～ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE: POLYPROPYLENE
TOP TAPE: PET, PE, PEF
REEL: POLYSTYREN (PS)
<RECYCLE MATERIAL CONTAINED>

- 本製品は54132-**61に対するニッケルバリア品である。
THIS PRODUCT IS Ni-Barrier OF 54132-**61.



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		ANGULAR	± --- °	MATERIAL NO.		DOCUMENT NO.			SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 4		SD-54132-064			3 OF 4		
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

